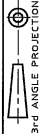


NUMBER 178295

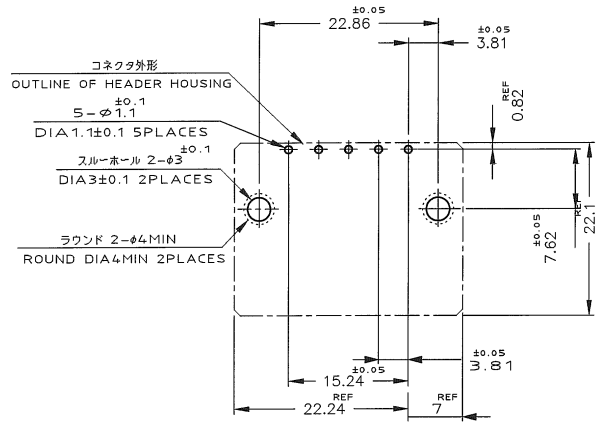
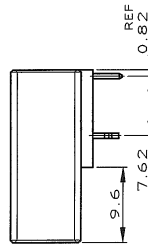
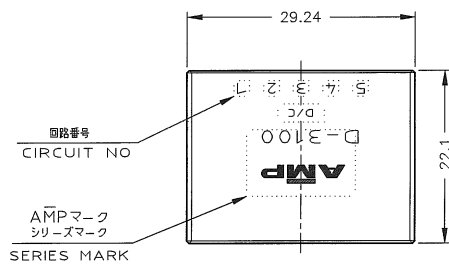


METRIC

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

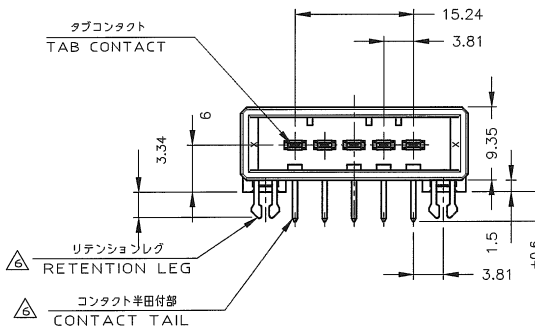
PRINT DIST

AMP-J  
REV.10/93



推奨基板取付け寸法  
PC 基板厚: 1.6±0.1  
(非累積公差)  
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN  
PC BOARD THICKNESS: 1.6±0.1  
(NOT ACCUMULATE TOLERANCE)  
(CONNECTOR MOUNT SIDE)



NOTES

- MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER  
CONTACT: COPPER ALLOY  
RETENTION LEG: COPPER ALLOY
- FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER NI PLATING
- FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER NI PLATING
- FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
- FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
- FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注記

- 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂  
コンタクト: 銅合金  
リテンションレグ: 銅合金
- めっき: コンタクト: 全面Ni下地  
接触部: 0.38 μm MIN 金めっき
- めっき: コンタクト: 全面Ni下地  
接触部: 0.76 μm MIN 金めっき
- めっき: コンタクト: 全面Ni下地  
接触部: 2.0 μm MIN スズめっき
- めっき: リテンションレグとコンタクト半田付部  
ニッケル下地の土は半田めっき
- めっき: リテンションレグとコンタクト半田付部: ニッケル下地の上にスズめっき

△	△	1-178295-5
△	△	1-178295-3
△	△	1-178295-2
(FINISH)		製品番号 (PART NO.)

LTR	REVISION RECORD	DR	CHK	DATE

WIRE RANGE		INSULATION DIA		NAME	
mm (AWG)		mm (mm)		5 POS SINGLE ROW	
MATERIAL		FINISH		HORIZONTAL HDR ASS'Y FOR DYNAMIC 3100	
SEE NOTE		SEE NOTE		NUMBER	
DR. 14 JUN 91		DE. 14 JUN 91		SCALE	
N. Matsudara		N. Matsudara		2-1	
CHK. 7/10/91		APP. S. MANABE		REV. B	
				SHEET 1 OF 1	

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GENERAL TOLERANCES			SIZE LOC NUMBER		
100% ±0.3			A3 J C-178295		
100% ±0.4					
20% ±0.5					
3% ±0.5					

(CUSTOMER DRAWING) 顧客用図面